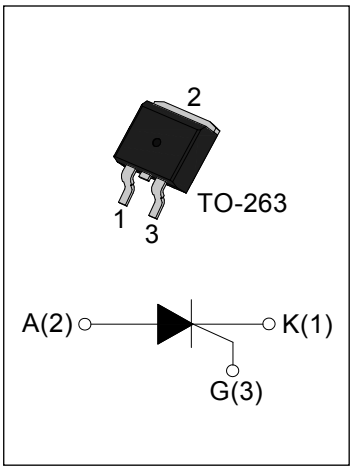
JCTx25 Series 25A SCRs

Rev.7.0

DESCRIPTION:

With high ability to withstand the shock loading of large current, JCTx25 SCRs provide high dv/dt rate with strong resistance to electromagnetic interference. They are especially recommended for use on solid state relay, motorcycle, power charger, T-tools etc. Package TO-263 is RoHS compliant. (2011/65/EU)



MAIN FEATURES

Symbol	JCT625	JCT825
V_{DRM}/ V_{RRM}	600V	800V
$I_{T(RMS)}$	25A	
I_{GT}	≤40mA	

ABSOLUTE MAXIMUM RATINGS

Parameter		Symbol	Value	Unit
Storage junction temperature range		T_{stg}	-40-150	℃
Operating junction temperature range		T_j	-40-150	℃
Repetitive peak off-state voltage(T_j=25℃)		V_{DRM}	600/800	V
Repetitive peak reverse voltage(T_j=25℃)		V_{RRM}	600/800	V
RMS on-state current	TO-263 (T_C=90℃)	$I_{T(RMS)}$	25	A
Non repetitive surge peak on-state current (tp=10ms)		I_{TSM}	300	A
I^2t value for fusing (tp=10ms)		I^2t	450	A^2s
Critical rate of rise of on-state current (I_G=2×I_{GT})		dI/dt	50	A/μs
Peak gate current		I_{GM}	4	A
Average gate power dissipation		$P_{G(AV)}$	1	W
Peak gate power		P_{GM}	5	W

ELECTRICAL CHARACTERISTICS (T_j=25℃ unless otherwise specified)

Symbol	Test Condition	Value			Unit
		MIN.	TYP.	MAX.	
I_{GT}	V_D=12V R_L=33Ω	-	-	40	mA
V_{GT}		-	-	1.3	V
V_{GD}	V_D=V_{DRM} T_j=150℃ R_L=3.3KΩ	0.2	-	-	V
I_L	I_G=1.2I_{GT}	-	-	90	mA
I_H	I_T=500mA	-	-	80	mA
dV/dt	V_D=2/3V_{DRM} Gate Open T_j=150℃	200	-	-	V/μs

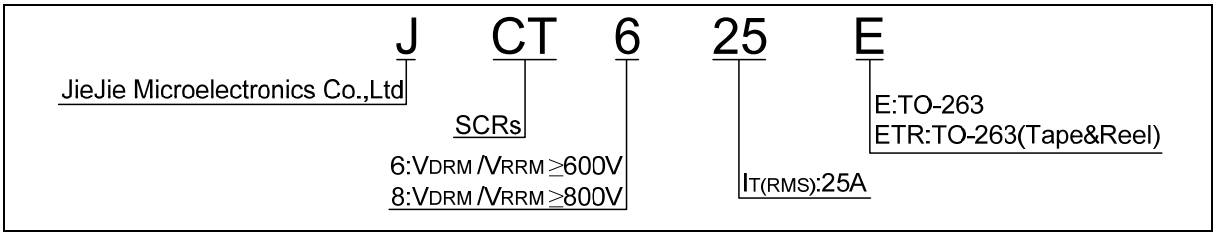
STATIC CHARACTERISTICS

Symbol	Parameter		Value(MAX)	Unit
V_{TM}	I_{TM}=50A tp=380μs	T_j=25℃	1.55	V
I_{DRM}	V_D=V_{DRM} V_R=V_{RRM}	T_j=25℃	10	μA
I_{RRM}		T_j=150℃	4	mA

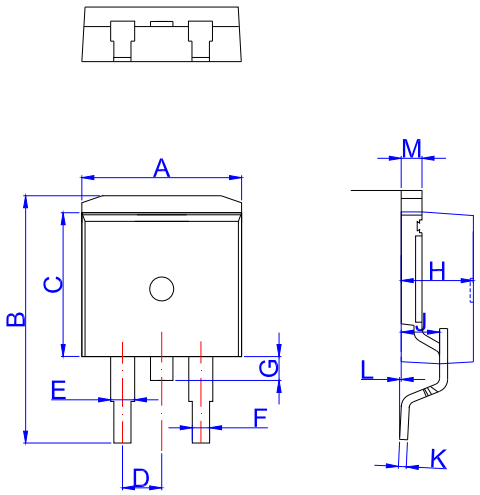
THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
$R_{th(j-c)}$	junction to case(AC)	TO-263	1.9	℃/W
$R_{th(j-a)}$	junction to ambient		45	

ORDERING INFORMATION



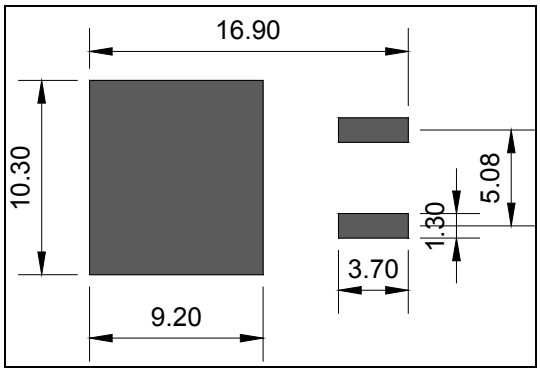
PACKAGE MECHANICAL DATA



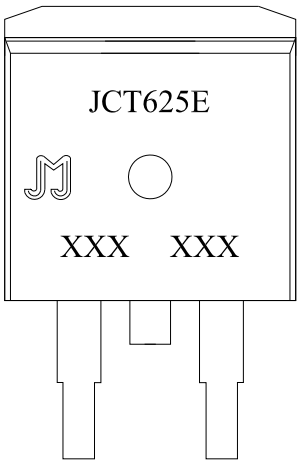
TO-263

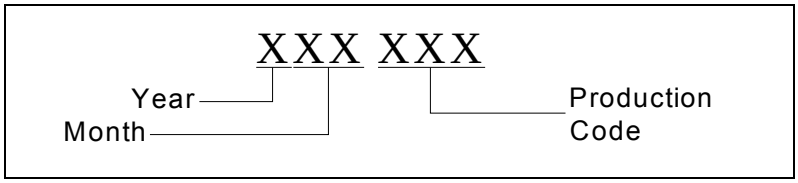
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	9.90		10.20	0.390		0.402
B	14.70		15.80	0.579		0.622
C	9.4		9.6	0.37		0.378
D		2.54			0.100	
E	1.20		1.40	0.047		0.055
F	0.75		0.85	0.029		0.033
G			1.75			0.069
H	4.40		4.70	0.173		0.185
J	2.30		2.70	0.091		0.106
K	0.38		0.55	0.015		0.022
L	0	0.10	0.25	0	0.004	0.010
M	1.25		1.35	0.049		0.053

FOOTPRINT-TO-263 (dimensions in mm)



MARKING





PACKAGE INFORMATION

PACKAGE	OUTLINE	TUBE (PCS)	INNER BOX (PCS)	PER CARTON
TO-263	TUBE	50	1,000	6,000
TO-263	TUBE	50	1,000	8,000
PACKAGE	**OUTLINE**	**REEL (PCS)**	**PER CARTON (PCS)**	**TAPE & REEL**
TO-263	TAPING	800	4,000	13 inch

FIG.1: Maximum power dissipation versus RMS on-state current

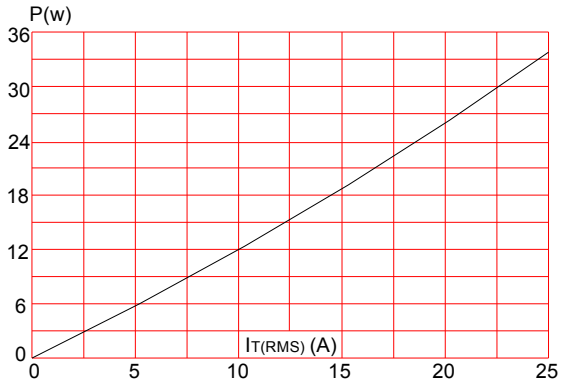


FIG.2: RMS on-state current versus ambient temperature (printed circuit board FR4, copper thickness:35μm)(full cycle)

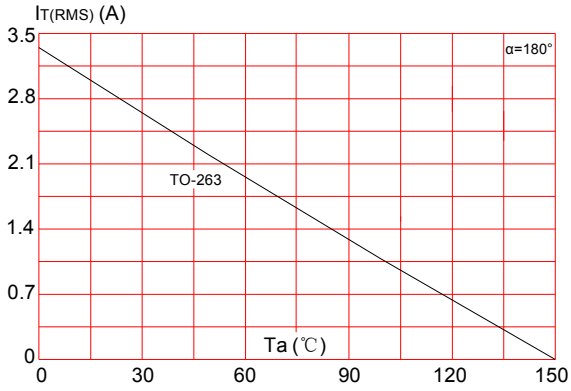


FIG.3: Surge peak on-state current versus number of cycles

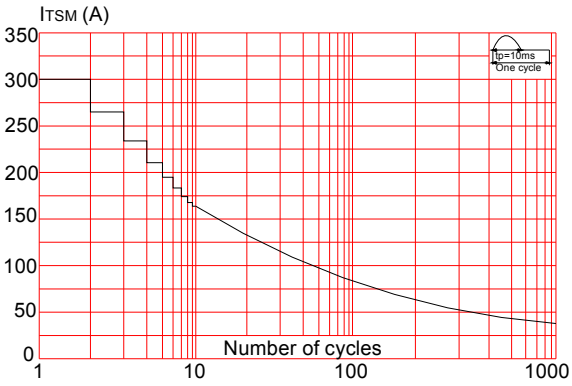


FIG.4: On-state characteristics (maximum values)

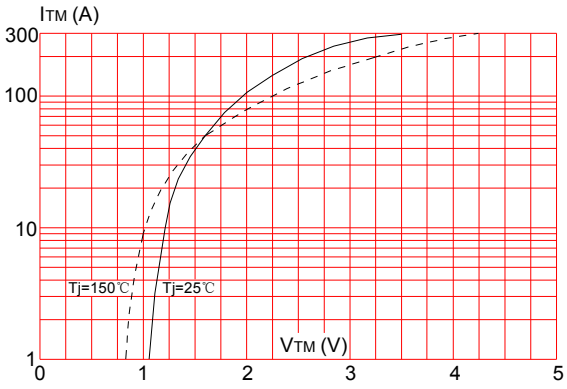


FIG.5: Non-repetitive surge peak on-state current for a sinusoidal pulse with width tp<10ms, and corresponging value of I^2t (dI/dt < 50A/μs)

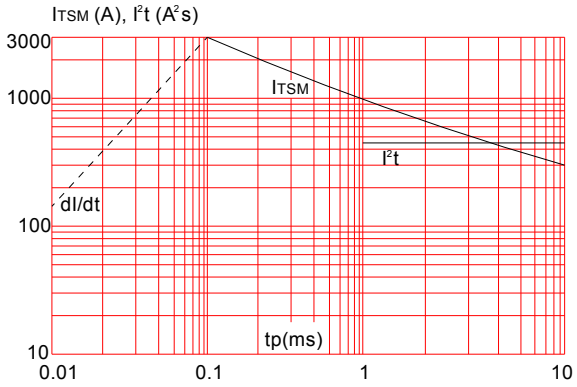
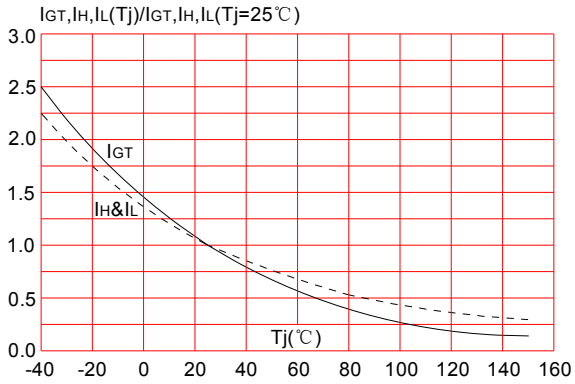
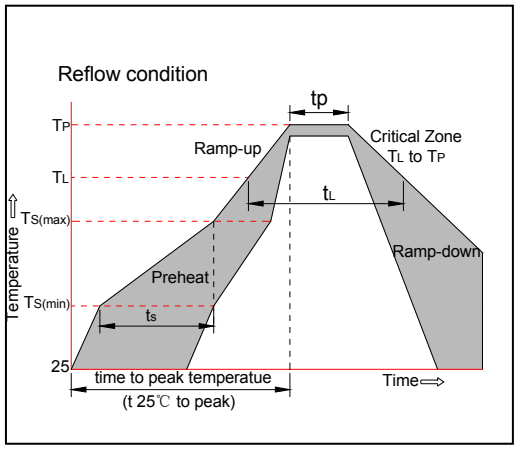


FIG.6: Relative variations of gate trigger current, holding current and latching current versus junction temperature



SOLDERING PARAMETERS

Reflow Condition		Pb-Free assembly (see figure at right)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150℃
	-Temperature Max ($T_{s(max)}$)	+200℃
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquidus Temp (T_L)to peak)		3℃/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3℃/sec. Max
Reflow	-Temperature(T_L) (Liquidus)	+217℃
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)℃
Time within 5℃of actual Peak Temp (t_p)		20-40secs.
Ramp-down Rate		6℃/sec. Max
Time 25℃ to Peak Temp (T_P)		8 min. Max
Do not exceed		+260℃



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